

# MJD2955 (PNP), MJD3055 (NPN)

## Complementary Power Transistors

### DPAK for Surface Mount Applications

Designed for general purpose amplifier and low speed switching applications.

#### Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Straight Lead Version in Plastic Sleeves (“-1” Suffix)
- Electrically Similar to MJE2955 and MJE3055
- High Current Gain-Bandwidth Product
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### MAXIMUM RATINGS

| Rating  | Symbol         | Max           | Unit                     |
|---|----------------|---------------|--------------------------|
| Collector-Emitter Voltage   | $V_{CEO}$      | 60            | Vdc                      |
| Collector-Base Voltage  | $V_{CB}$       | 70            | Vdc                      |
| Emitter-Base Voltage  | $V_{EB}$       | 5             | Vdc                      |
| Collector Current   | $I_C$          | 10            | Adc                      |
| Base Current  | $I_B$          | 6             | Adc                      |
| Total Power Dissipation<br>@ $T_C = 25^\circ\text{C}$<br>Derate above $25^\circ\text{C}$          | $P_D^\dagger$  | 20<br>0.16    | W<br>W/ $^\circ\text{C}$ |
| Total Power Dissipation (Note 1)<br>@ $T_A = 25^\circ\text{C}$<br>Derate above $25^\circ\text{C}$ | $P_D$          | 1.75<br>0.014 | W<br>W/ $^\circ\text{C}$ |
| Operating and Storage Junction<br>Temperature Range   | $T_J, T_{stg}$ | -55 to +150   | $^\circ\text{C}$         |
| ESD - Human Body Model  | HBM            | 3B            | V                        |
| ESD - Machine Model   | MM             | C             | V                        |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Safe Area Curves are indicated by Figure 1. Both limits are applicable and must be observed.

1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

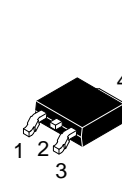
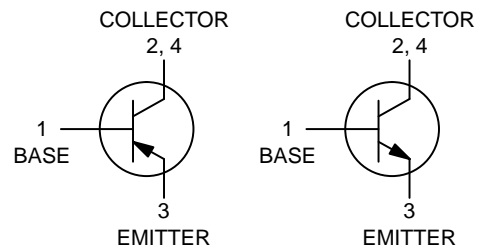


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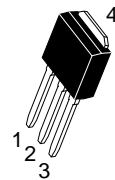
<http://onsemi.com>

### SILICON POWER TRANSISTORS 10 AMPERES 60 VOLTS, 20 WATTS

#### COMPLEMENTARY

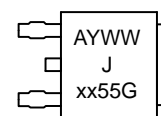


**DPAK  
CASE 369C  
STYLE 1**

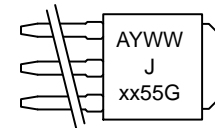


**IPAK  
CASE 369D  
STYLE 1**

#### MARKING DIAGRAMS



DPAK



IPAK

- A = Assembly Location
- Y = Year
- WW = Work Week
- Jxx55 = Device Code  
x = 29 or 30
- G = Pb-Free Package

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

# MJD2955 (PNP), MJD3055 (NPN)

## THERMAL CHARACTERISTICS

| Characteristic                                   | Symbol          | Max  | Unit          |
|--|-----------------|------|---------------|
| Thermal Resistance, Junction-to-Case             | $R_{\theta JC}$ | 6.25 | $^{\circ}C/W$ |
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 71.4 | $^{\circ}C/W$ |

2. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

## ELECTRICAL CHARACTERISTICS ( $T_C = 25^{\circ}C$ unless otherwise noted)

| Characteristic | Symbol | Min | Max | Unit |
|----------------|--------|-----|-----|------|
|----------------|--------|-----|-----|------|

### OFF CHARACTERISTICS

|   |               |    |                  |                 |
|---|---------------|----|------------------|-----------------|
| Collector-Emitter Sustaining Voltage (Note 3)<br>( $I_C = 30 \text{ mAdc}$ , $I_B = 0$ )  | $V_{CE(sus)}$ | 60 | –                | Vdc             |
| Collector Cutoff Current<br>( $V_{CE} = 30 \text{ Vdc}$ , $I_B = 0$ )   | $I_{CEO}$     | –  | 50               | $\mu\text{Adc}$ |
| Collector Cutoff Current<br>( $V_{CE} = 70 \text{ Vdc}$ , $V_{EB(off)} = 1.5 \text{ Vdc}$ )<br>( $V_{CE} = 70 \text{ Vdc}$ , $V_{EB(off)} = 1.5 \text{ Vdc}$ , $T_C = 150^{\circ}C$ ) | $I_{CEX}$     | –  | $\frac{0.02}{2}$ | mAdc            |
| Collector Cutoff Current<br>( $V_{CB} = 70 \text{ Vdc}$ , $I_E = 0$ )<br>( $V_{CB} = 70 \text{ Vdc}$ , $I_E = 0$ , $T_C = 150^{\circ}C$ )   | $I_{CBO}$     | –  | $\frac{0.02}{2}$ | mAdc            |
| Emitter Cutoff Current<br>( $V_{BE} = 5 \text{ Vdc}$ , $I_C = 0$ )  | $I_{EBO}$     | –  | 0.5              | mAdc            |

### ON CHARACTERISTICS

|  |               |                |                 |     |
|--|---------------|----------------|-----------------|-----|
| DC Current Gain (Note 3)<br>( $I_C = 4 \text{ Adc}$ , $V_{CE} = 4 \text{ Vdc}$ )<br>( $I_C = 10 \text{ Adc}$ , $V_{CE} = 4 \text{ Vdc}$ )                    | $h_{FE}$      | $\frac{20}{5}$ | $\frac{100}{-}$ | –   |
| Collector-Emitter Saturation Voltage (Note 3)<br>( $I_C = 4 \text{ Adc}$ , $I_B = 0.4 \text{ Adc}$ )<br>( $I_C = 10 \text{ Adc}$ , $I_B = 3.3 \text{ Adc}$ ) | $V_{CE(sat)}$ | –              | $\frac{1.1}{8}$ | Vdc |
| Base-Emitter On Voltage (Note 3)<br>( $I_C = 4 \text{ Adc}$ , $V_{CE} = 4 \text{ Vdc}$ )   | $V_{BE(on)}$  | –              | 1.8             | Vdc |

### DYNAMIC CHARACTERISTICS

|  |       |   |   |     |
|--|-------|---|---|-----|
| Current-Gain – Bandwidth Product<br>( $I_C = 500 \text{ mAdc}$ , $V_{CE} = 10 \text{ Vdc}$ , $f = 500 \text{ kHz}$ ) | $f_T$ | 2 | – | MHz |
|--|-------|---|---|-----|

3. Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

# MJD2955 (PNP), MJD3055 (NPN)

## TYPICAL CHARACTERISTICS

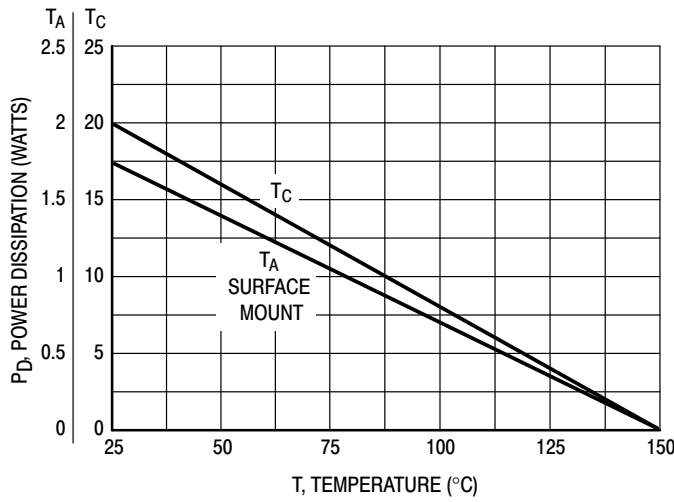


Figure 1. Power Derating

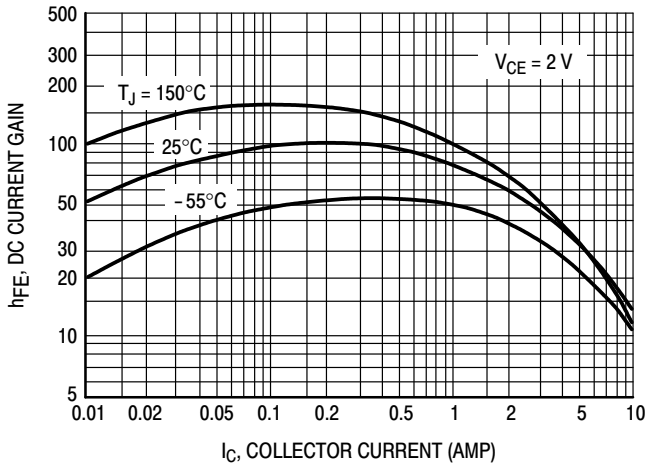


Figure 2. DC Current Gain

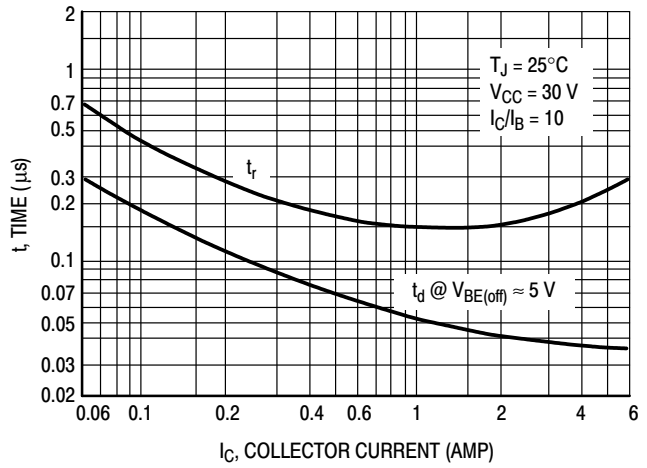


Figure 3. Turn-On Time

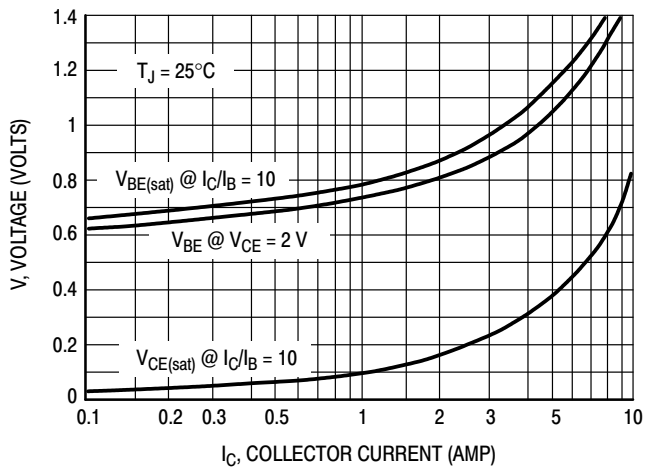


Figure 4. "On" Voltages, MJD3055

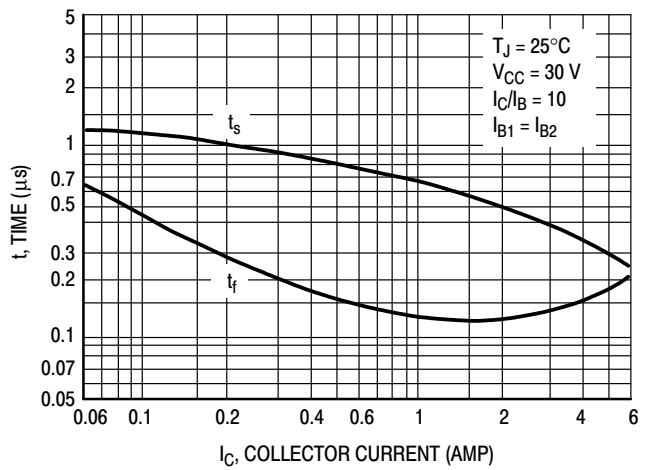


Figure 5. Turn-Off Time

## MJD2955 (PNP), MJD3055 (NPN)

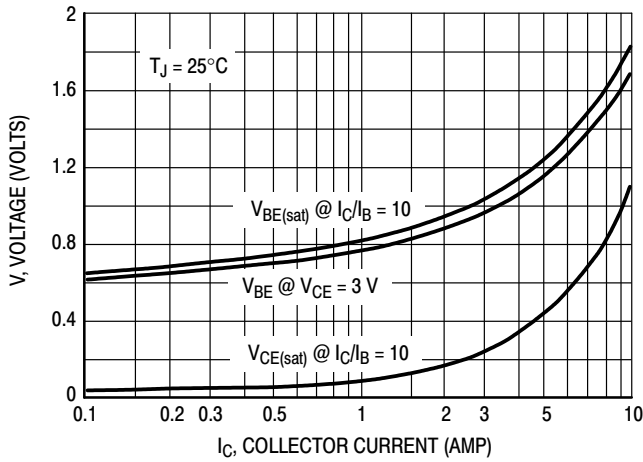


Figure 6. "On" Voltages, MJD2955

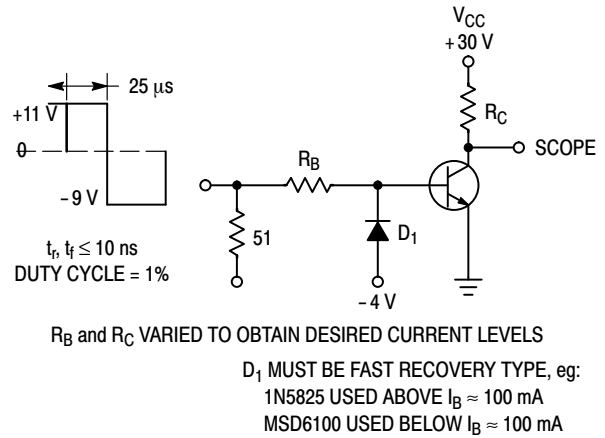


Figure 7. Switching Time Test Circuit

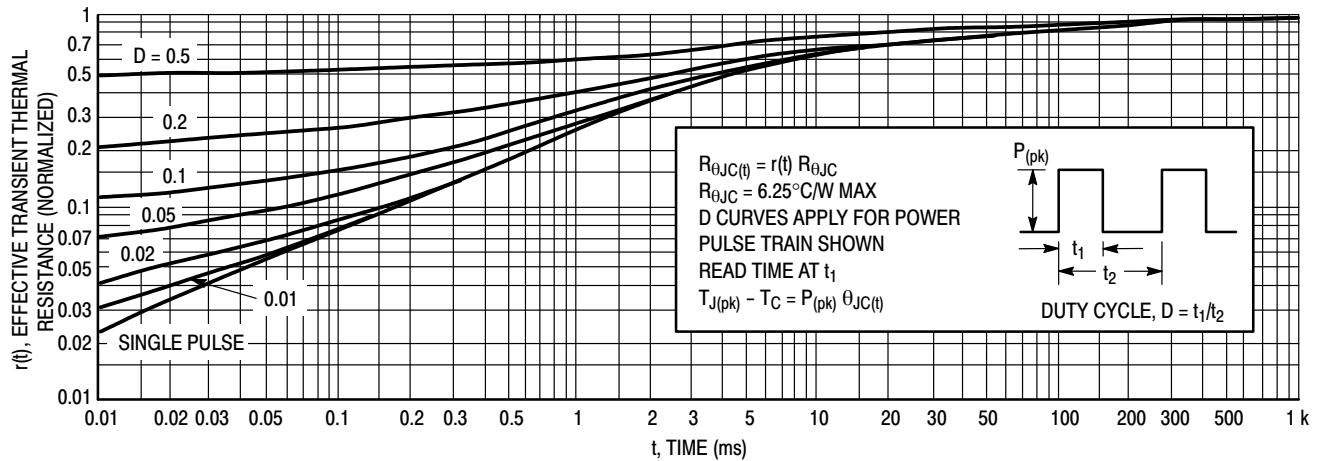


Figure 8. Thermal Response

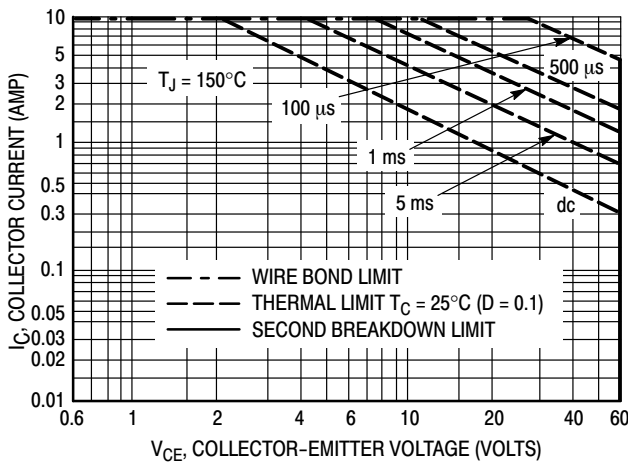


Figure 9. Maximum Forward Bias Safe Operating Area

### Forward Bias Safe Operating Area Information

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 9 is based on  $T_{J(pk)} = 150^\circ\text{C}$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} \leq 150^\circ\text{C}$ .  $T_{J(pk)}$  may be calculated from the data in Figure 8. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

## MJD2955 (PNP), MJD3055 (NPN)

### ORDERING INFORMATION

| Device         | Package Type      | Package | Shipping <sup>†</sup> |
|----------------|-------------------|---------|-----------------------|
| MJD2955G       | DPAK<br>(Pb-Free) | 369C    | 75 Units / Rail       |
| MJD2955-1G     | IPAK<br>(Pb-Free) | 369D    | 75 Units / Rail       |
| MJD2955T4G     | DPAK<br>(Pb-Free) | 369C    | 2,500 / Tape & Reel   |
| NJVMJD2955T4G* | DPAK<br>(Pb-Free) | 369C    | 2,500 / Tape & Reel   |
| MJD3055G       | DPAK<br>(Pb-Free) | 369C    | 75 Units / Rail       |
| MJD3055T4G     | DPAK<br>(Pb-Free) | 369C    | 2,500 / Tape & Reel   |
| NJVMJD3055T4G* | DPAK<br>(Pb-Free) | 369C    | 2,500 / Tape & Reel   |

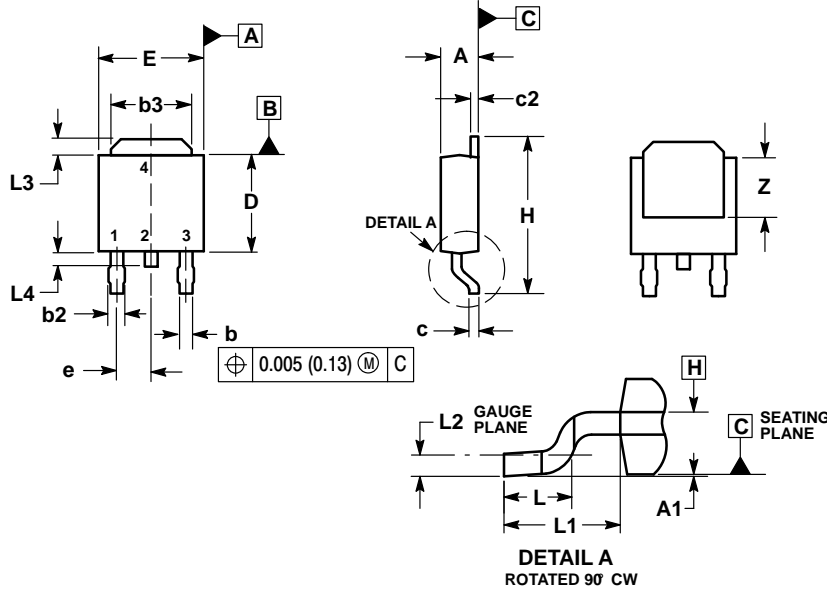
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

# MJD2955 (PNP), MJD3055 (NPN)

## PACKAGE DIMENSIONS

### DPAK (SINGLE GAUGE) CASE 369C ISSUE D



**NOTES:**

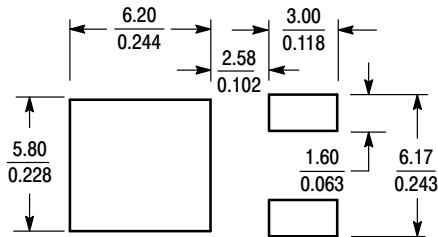
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

| DIM | INCHES    |       | MILLIMETERS |       |
|-----|-----------|-------|-------------|-------|
|     | MIN       | MAX   | MIN         | MAX   |
| A   | 0.086     | 0.094 | 2.18        | 2.38  |
| A1  | 0.000     | 0.005 | 0.00        | 0.13  |
| b   | 0.025     | 0.035 | 0.63        | 0.89  |
| b2  | 0.030     | 0.045 | 0.76        | 1.14  |
| b3  | 0.180     | 0.215 | 4.57        | 5.46  |
| c   | 0.018     | 0.024 | 0.46        | 0.61  |
| c2  | 0.018     | 0.024 | 0.46        | 0.61  |
| D   | 0.235     | 0.245 | 5.97        | 6.22  |
| E   | 0.250     | 0.265 | 6.35        | 6.73  |
| e   | 0.090 BSC |       | 2.29 BSC    |       |
| H   | 0.370     | 0.410 | 9.40        | 10.41 |
| L   | 0.055     | 0.070 | 1.40        | 1.78  |
| L1  | 0.108 REF |       | 2.74 REF    |       |
| L2  | 0.020 BSC |       | 0.51 BSC    |       |
| L3  | 0.035     | 0.050 | 0.89        | 1.27  |
| L4  | ---       | 0.040 | ---         | 1.01  |
| Z   | 0.155     | ---   | 3.93        | ---   |

**STYLE 1:**

1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

### SOLDERING FOOTPRINT\*



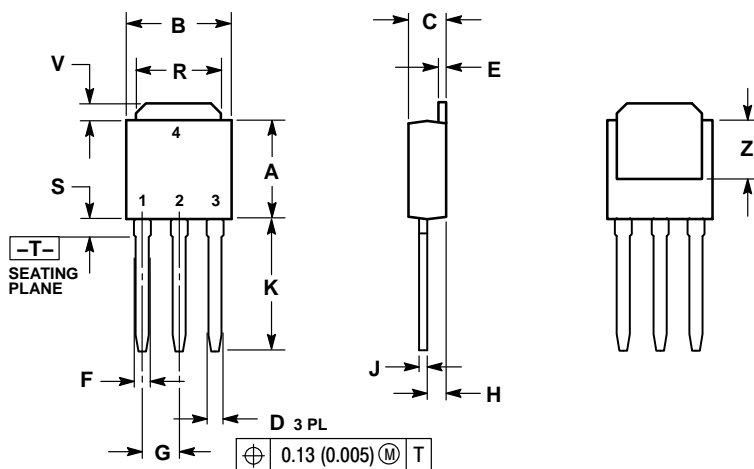
SCALE 3:1  $\left(\frac{\text{mm}}{\text{inches}}\right)$

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MJD2955 (PNP), MJD3055 (NPN)

## PACKAGE DIMENSIONS

### IPAK CASE 369D ISSUE C



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

| DIM | INCHES |       | MILLIMETERS |      |
|-----|--------|-------|-------------|------|
|     | MIN    | MAX   | MIN         | MAX  |
| A   | 0.235  | 0.245 | 5.97        | 6.35 |
| B   | 0.250  | 0.265 | 6.35        | 6.73 |
| C   | 0.086  | 0.094 | 2.19        | 2.38 |
| D   | 0.027  | 0.035 | 0.69        | 0.88 |
| E   | 0.018  | 0.023 | 0.46        | 0.58 |
| F   | 0.037  | 0.045 | 0.94        | 1.14 |
| G   | 0.090  | BSC   | 2.29        | BSC  |
| H   | 0.034  | 0.040 | 0.87        | 1.01 |
| J   | 0.018  | 0.023 | 0.46        | 0.58 |
| K   | 0.350  | 0.380 | 8.89        | 9.65 |
| R   | 0.180  | 0.215 | 4.45        | 5.45 |
| S   | 0.025  | 0.040 | 0.63        | 1.01 |
| V   | 0.035  | 0.050 | 0.89        | 1.27 |
| Z   | 0.155  | ---   | 3.93        | ---  |

- STYLE 1:
1. BASE
  2. COLLECTOR
  3. EMITTER
  4. COLLECTOR

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